



Material Content Data Sheet



Sales Product Name		BSP88 H6327		Issued		20. July 2018		
MA#		MA001097590						
Package		PG-SOT223-4-21		Weight*		113.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.026	0.02		228	
	non noble metal	tin	7440-31-5	0.007	0.01		59	
	inorganic material	silicon	7440-21-3	0.294	0.26	0.29	2590	2877
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		447	
	non noble metal	chromium	7440-47-3	0.152	0.13		1340	
	non noble metal	copper	7440-50-8	50.489	44.49	44.67	444909	446785
wire	non noble metal	copper	7440-50-8	0.019	0.02	0.02	165	165
encapsulation	organic material	carbon black	1333-86-4	0.605	0.53		5328	
	plastics	epoxy resin	-	9.069	7.99		79913	
	inorganic material	silicondioxide	60676-86-0	50.785	44.76	53.28	447510	532751
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12901	12901
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4521	4521
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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